

May 2001

QFET™

FQPF13N06

60V N-Channel MOSFET

General Description

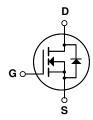
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as DC/DC converters, high efficiency switching for power management in portable and battery operated products.

Features

- 9.4A, 60V, $R_{DS(on)} = 0.135\Omega @V_{GS} = 10 V$
- Low gate charge (typical 5.8 nC)
- · Low Crss (typical 15 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

| Symbol | Parameter | | FQPF13N06 | Units |
|-----------------------------------|---|----------|-------------|-------|
| V _{DSS} | Drain-Source Voltage | | 60 | V |
| I _D | Drain Current - Continuous (T _C = 25 | °C) | 9.4 | Α |
| | - Continuous (T _C = 100°C) | | 6.6 | Α |
| I _{DM} | Drain Current - Pulsed | (Note 1) | 37.6 | А |
| V _{GSS} | Gate-Source Voltage | | ± 25 | V |
| E _{AS} | Single Pulsed Avalanche Energy | (Note 2) | 85 | mJ |
| I _{AR} | Avalanche Current | (Note 1) | 9.4 | А |
| E _{AR} | Repetitive Avalanche Energy | (Note 1) | 2.4 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | (Note 3) | 7.0 | V/ns |
| P _D | Power Dissipation (T _C = 25°C) | | 24 | W |
| | - Derate above 25°C | | 0.16 | W/°C |
| T _J , T _{STG} | Operating and Storage Temperature Range | | -55 to +175 | °C |
| T _L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 300 | °C |

Thermal Characteristics

| Symbol | Parameter | Тур | Max | Units |
|-----------------|---|-----|------|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | | 6.2 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | 62.5 | °C/W |

| Symbol | Parameter | Test Conditions | | Min | Тур | Max | Units |
|------------------------------------|---|--|-----------|-----|-------|-------|-------|
| Off Cha | racteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 60 | | | ٧ |
| ΔBV_{DSS} / ΔT_{J} | Breakdown Voltage Temperature Coefficient | I _D = 250 μA, Referenced to 25°C | 0 | | 0.06 | | V/°C |
| I _{DSS} | Zarra Cata Valta da Duais Comunant | V _{DS} = 60 V, V _{GS} = 0 V | | | | 1 | μΑ |
| | Zero Gate Voltage Drain Current | V _{DS} = 48 V, T _C = 150°C | | | | 10 | μΑ |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 25 V, V _{DS} = 0 V | | | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$ | | | | -100 | nA |
| On Cha | racteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | | 2.0 | | 4.0 | V |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 4.7 A | | | 0.105 | 0.135 | Ω |
| 9 _{FS} | Forward Transconductance | 40 5 | (Note 4) | | 4.8 | | S |
| C _{iss} | Input Capacitance | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz | | | 240 | 310 | pF |
| C _{oss} | Output Capacitance | | | | 90 | 120 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | | 15 | 20 | pF |
| Switchi | ng Characteristics | | | | | | |
| t _{d(on)} | Turn-On Delay Time | V 00.V I 0.5.A | | | 5 | 20 | ns |
| t _r | Turn-On Rise Time | $V_{DD} = 30 \text{ V}, I_{D} = 6.5 \text{ A},$ $R_{G} = 25 \Omega$ | | | 25 | 60 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | | 8 | 25 | ns |
| t _f | Turn-Off Fall Time | (N | ote 4, 5) | | 15 | 40 | ns |
| Qg | Total Gate Charge | V _{DS} = 48 V, I _D = 13 A, | | | 5.8 | 7.5 | nC |
| Q _{gs} | Gate-Source Charge | V _{GS} = 10 V | Ī | | 2.0 | | nC |
| Q _{gd} | Gate-Drain Charge | (N | ote 4, 5) | | 2.5 | - | nC |
| Drain-S | ource Diode Characteristics a | nd Maximum Ratings | | | | | |
| I _S | Maximum Continuous Drain-Source Diode Forward Current | | | | | 9.4 | Α |
| I _{SM} | Maximum Pulsed Drain-Source Diode F | Forward Current | | | | 37.6 | Α |
| V _{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_S = 9.4 \text{ A}$ | | | | 1.5 | V |
| t _{rr} | Reverse Recovery Time | $V_{GS} = 0 \text{ V}, I_{S} = 13 \text{ A},$ | | | 39 | | ns |
| Q _{rr} | Reverse Recovery Charge | dI _F / dt = 100 A/μs | (Note 4) | | 40 | | nC |

- Notes:
 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 1.12mH, I $_{AS}$ = 9.4A, V $_{DD}$ = 25V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C 3. I $_{SD}$ ≤ 13A, di/dt ≤ 300A/us, V $_{DD}$ ≤ BV $_{DSS}$, Starting T $_{J}$ = 25°C 4. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics

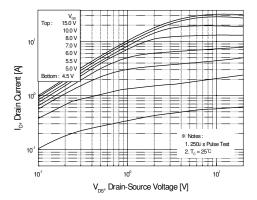


Figure 1. On-Region Characteristics

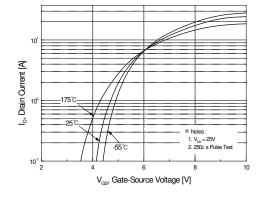


Figure 2. Transfer Characteristics

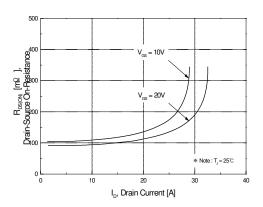


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

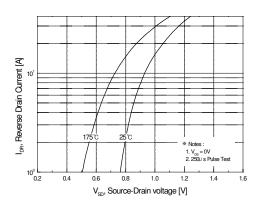


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

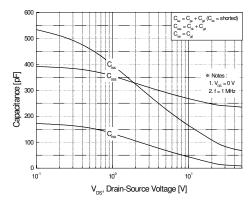


Figure 5. Capacitance Characteristics

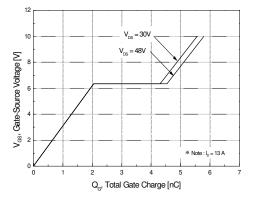
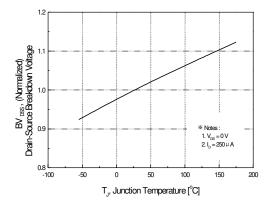


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



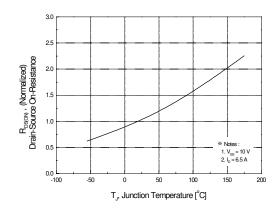
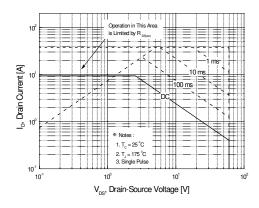


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



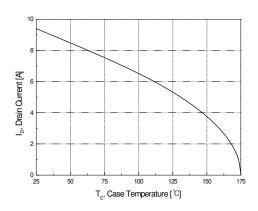


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

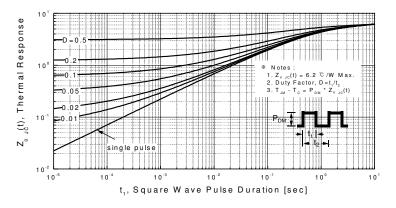
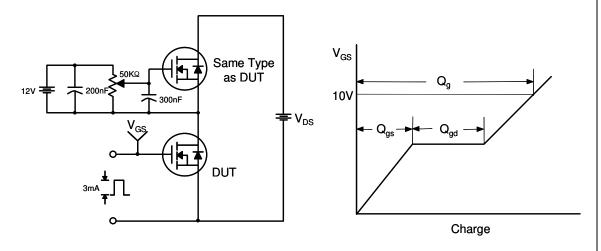


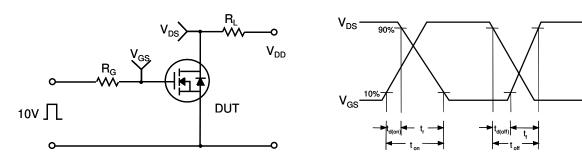
Figure 11. Transient Thermal Response Curve

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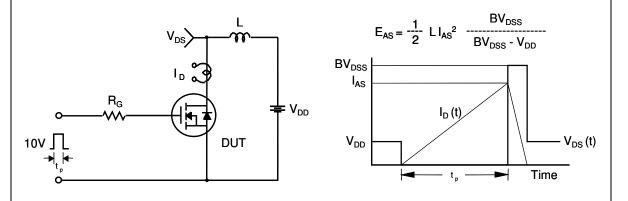
Gate Charge Test Circuit & Waveform



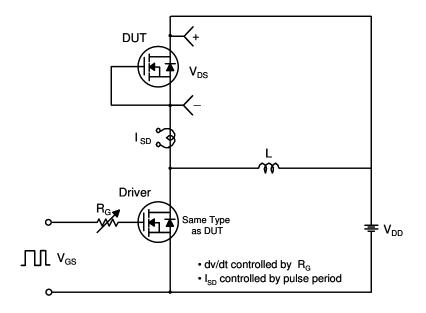
Resistive Switching Test Circuit & Waveforms

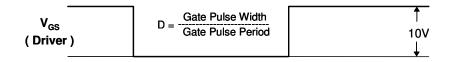


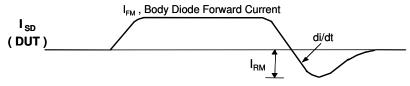
Unclamped Inductive Switching Test Circuit & Waveforms



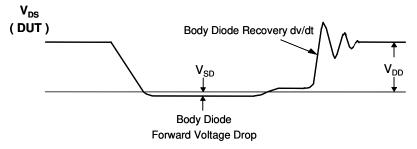
Peak Diode Recovery dv/dt Test Circuit & Waveforms

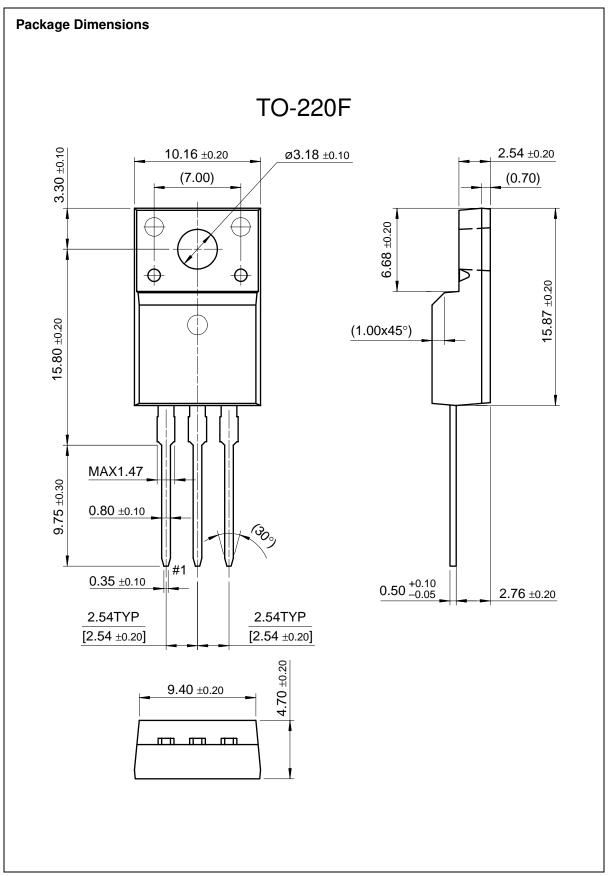






Body Diode Reverse Current





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